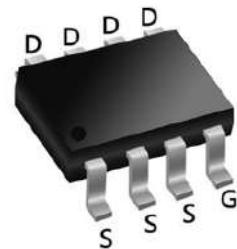


## N-Ch 30V Fast Switching MOSFETs

### Features:

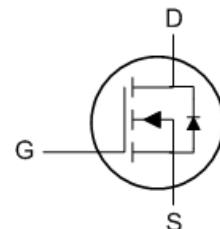
- Advanced Trench MOS Technology
- Low Gate Charge
- Low  $R_{DS(ON)}$
- 100% EAS Guaranteed
- Green Device Available



### Applications:

#### SOP8 Pin Configuration

- Power Management in Desktop Computer or DC/DC Converters.
- Isolated DC/DC Converters in Telecom and Industrial.



### Product Summary

BVDSS	RDSON	ID
30V	8.0mΩ	15A

### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_A=25^\circ C$	Continuous Drain Current <sup>1</sup>	15	A
$I_D @ T_A=70^\circ C$	Continuous Drain Current <sup>1</sup>	12	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	60	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	39.2	mJ
$I_{AS}$	Avalanche Current	28	A
$P_D @ T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	3.1	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	75	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup> , $t \leq 10\text{sec}$	---	40	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	24	°C/W

**N-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	30	---	---	V
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10\text{V}$ , $I_D=12\text{A}$	---	6.0	8	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=12\text{A}$	---	9.4	11	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu\text{A}$	1.2	1.7	2.2	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=30\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{DS}=30\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=5\text{V}$ , $I_D=12\text{A}$	---	55	---	S
$R_g$	Gate Resistance	$V_{DS}=0\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	0.8	1.7	2.6	$\Omega$
$Q_g$	Total Gate Charge (4.5V)	$V_{DS}=15\text{V}$ , $V_{GS}=10\text{V}$ , $I_D=12\text{A}$	---	7.1	---	$\text{nC}$
$Q_{gs}$	Gate-Source Charge		---	2.2	---	
$Q_{gd}$	Gate-Drain Charge		---	3.1	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=15\text{V}$ , $V_{GS}=10\text{V}$ , $R_G=3\Omega$ $I_D=12\text{A}$	---	7	---	$\text{ns}$
$T_r$	Rise Time		---	18.8	---	
$T_{d(off)}$	Turn-Off Delay Time		---	19.5	---	
$T_f$	Fall Time		---	3.4	---	
$C_{iss}$	Input Capacitance	$V_{DS}=15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	693	---	$\text{pF}$
$C_{oss}$	Output Capacitance		---	332	---	
$C_{rss}$	Reverse Transfer Capacitance		---	34	---	

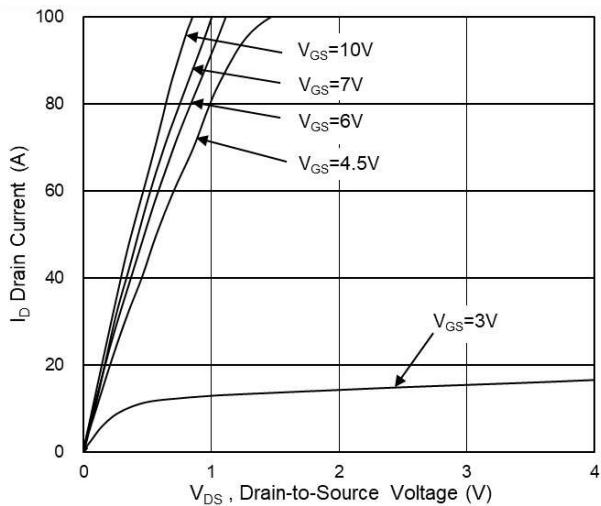
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	12	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V

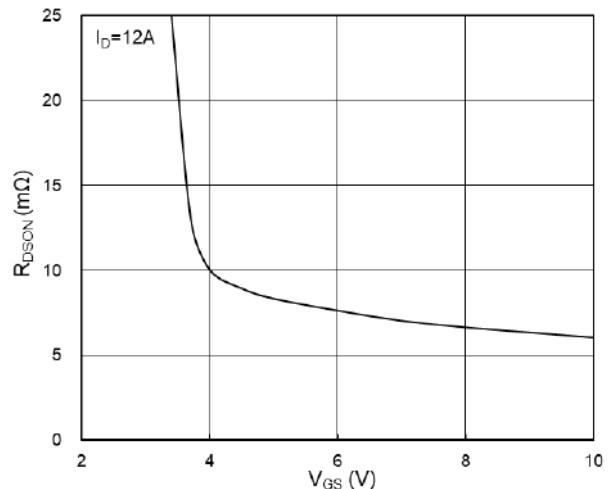
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25\text{V}$ , $V_{GS}=10\text{V}$ , $L=0.1\text{mH}$ , $I_{AS}=28\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

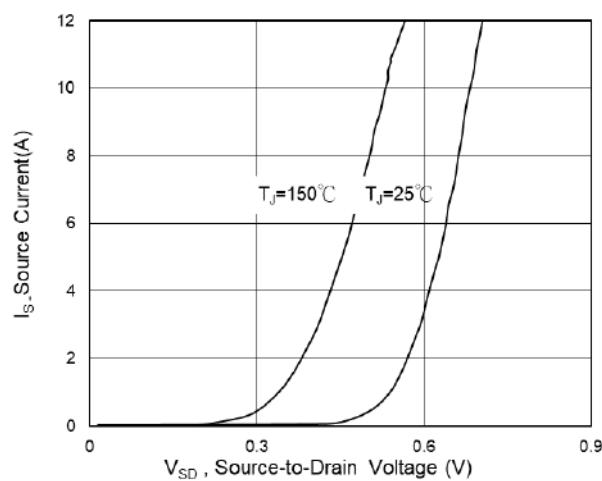
### Typical Characteristics



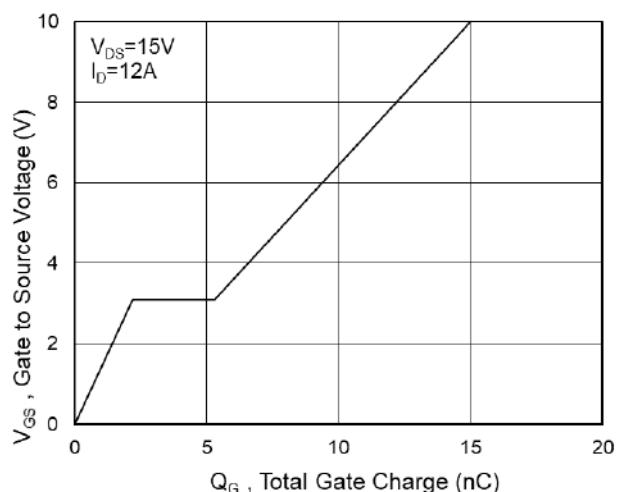
**Fig.1 Typical Output Characteristics**



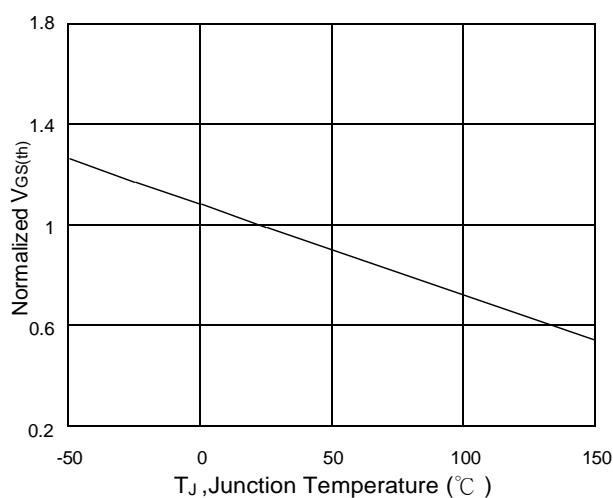
**Fig.2 On-Resistance vs G-S Voltage**



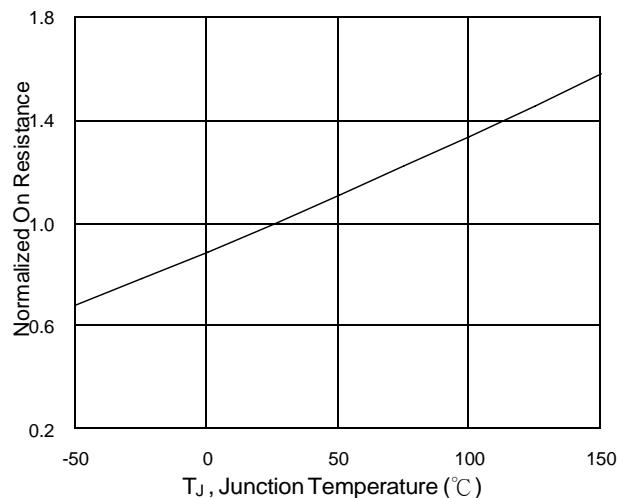
**Fig.3 Source Drain Forward Characteristics**



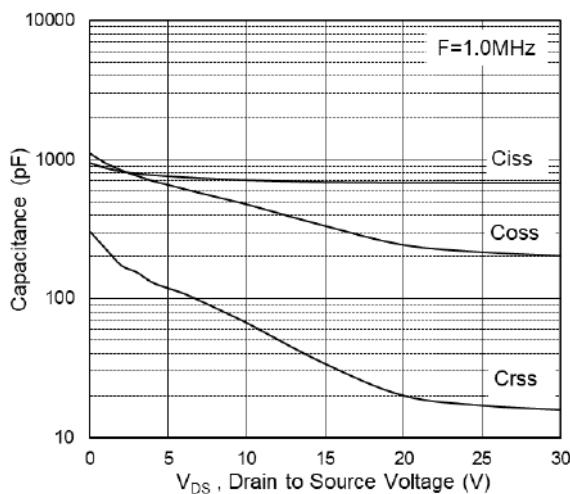
**Fig.4 Gate-Charge Characteristics**



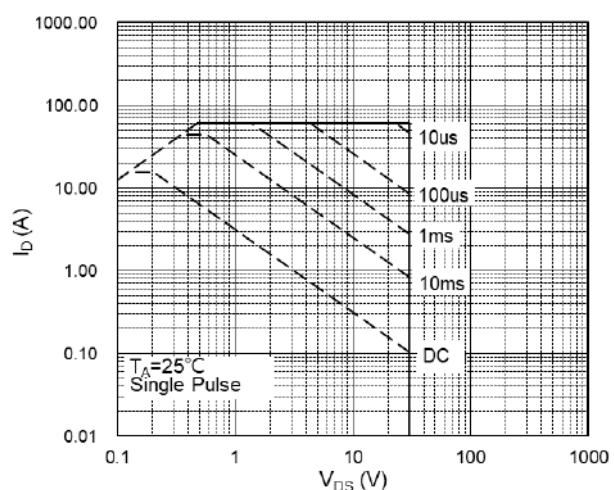
**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**



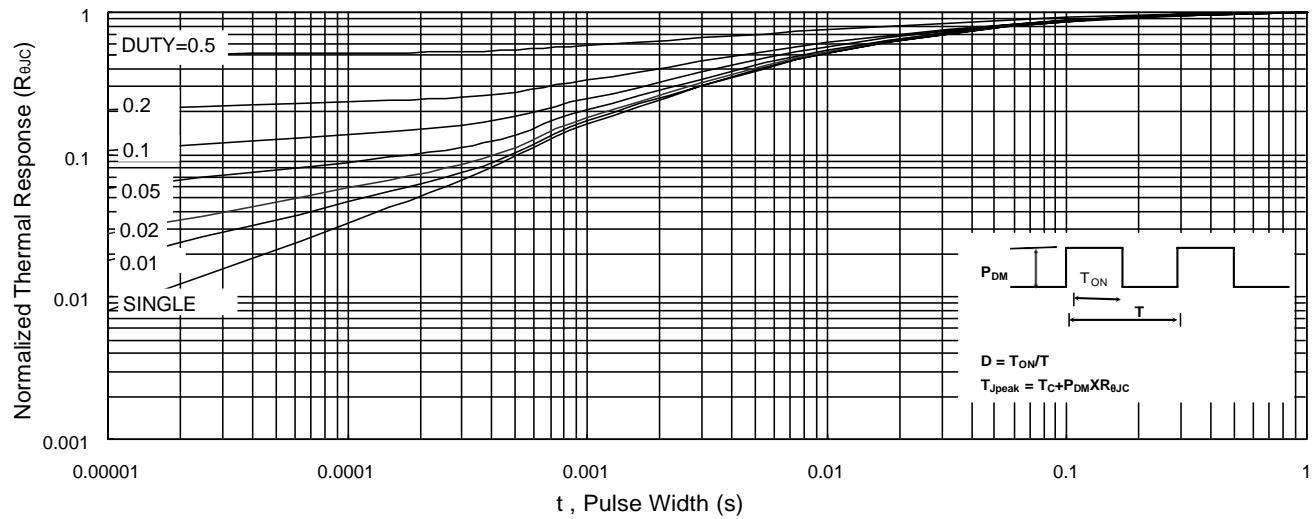
**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**



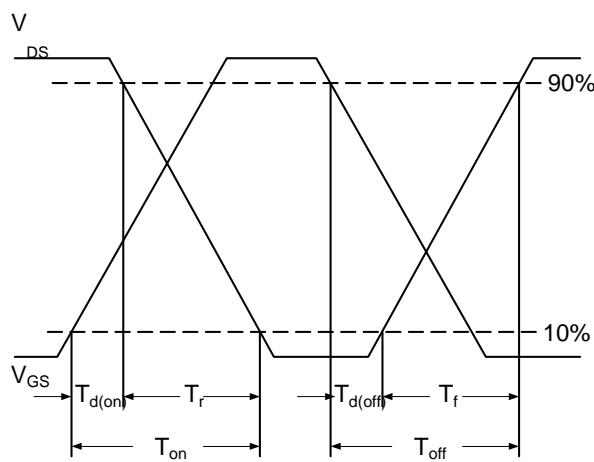
**Fig.7 Capacitance**



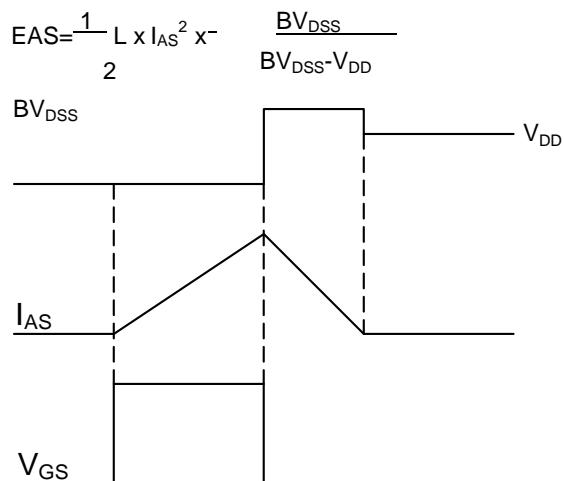
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**